

# HybridPACK™ Drive Module

FS660R08A6P2FLB

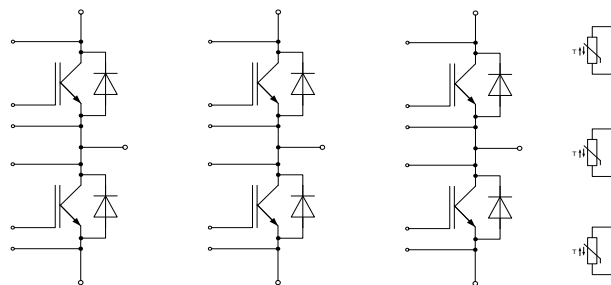
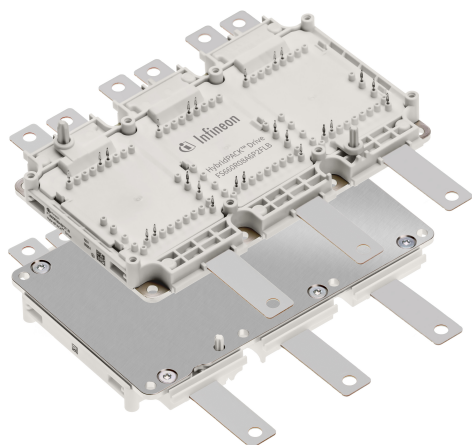
Final Data Sheet

V3.0, 2019-05-20

Automotive High Power

## 1 Features / Description

HybridPACK™ Drive module with EDT2 IGBT and Diode



$V_{CES} = 750 \text{ V}$   
 $I_C = 660 \text{ A}$

### Typical Applications

- Automotive Applications
- Hybrid Electrical Vehicles (H)EV
- Motor Drives
- Commercial Agriculture Vehicles

### Electrical Features

- Blocking voltage 750V
- Low  $V_{CEsat}$
- Low Switching Losses
- Low  $Q_g$  and  $Crss$
- Low Inductive Design
- $T_{vj\ op} = 150^\circ\text{C}$
- Short-time extended Operation Temperature  
 $T_{vj\ op} = 175^\circ\text{C}$

### Mechanical Features

- 4.2kV DC 1sec Insulation
- High Creepage and Clearance Distances
- Compact design
- High Power Density
- Copper Base Plate
- Guiding elements for PCB and cooler assembly
- Integrated NTC temperature sensor
- PressFIT Contact Technology
- RoHS compliant
- UL 94 V0 module frame

### Description

The HybridPACK™ Drive is a very compact six-pack module optimized for hybrid and electric vehicles. The product FS660R08A6P2FLB comes with a flat baseplate and is a 750V/660A module derivate within the HybridPACK Drive family. The power module implements the new EDT2 IGBT generation, which is an automotive Micro-Pattern Trench-Field-Stop cell design optimized for electric drive train applications. The chipset has benchmark current density combined with short circuit ruggedness and increased blocking voltage for reliable inverter operation under harsh environmental conditions. The EDT2 IGBTs also show excellent light load power losses, which helps to improve system efficiency over a real driving cycle. The EDT2 IGBT was optimized for applications with switching frequencies in the range of 10 kHz.

The new The HybridPACK™ Drive power module family comes with mechanical guiding elements supporting easy assembly processes for customers. Furthermore, the press-fit pins for the signal terminals avoid additional time consuming selective solder processes, which provides cost savings on system level and increases system reliability. The two products in the The HybridPACK™ Drive family with flat baseplate in the FS660R08A6P2FLB and PinFin baseplate in the FS820R08A6P2LB allow a very cost effective scaling for different inverter power levels at a minimum inverter design effort.

Product Name	Ordering Code
FS660R08A6P2FLB	SP001850450